

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component by laminating a plurality of multi-layered units each formed by laminating a ceramic green sheet, an electrode layer and a release layer on a support sheet in this order, the method comprising steps of positioning the multi-layered unit on a base substrate so that the surface of the release layer of the multi-layered unit is in contact with an agglutinant layer formed on the surface of the base substrate in such a manner that the bonding strength between itself and the ~~support~~base substrate is higher than the bonding strength between the support sheet and the ceramic green sheet and lower than the bonding strength between itself and the release layer, pressing it and laminating multi-layered units on the base substrate.

2.-18. (Cancelled)

19. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, which further comprises steps of peeling off the support sheet from the ceramic green sheet of the multi-layered unit laminated on the base substrate, laminating a new multi-layered unit in which an adhesive layer is formed on the surface of a release layer onto the ceramic green sheet of the multi-layered unit laminated on the base substrate via the adhesive layer, peeling off the support sheet from the ceramic green sheet of the newly laminated multi-layered unit and repeating the lamination of a new multi-layered unit in which an adhesive layer is formed on the surface of a release layer onto the ceramic green sheet of the multi-layered unit last laminated on the base substrate via the adhesive layer and peeling off of the support substrate from the ceramic green sheet of the last laminated multi-layered unit.

20. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer has a thickness of 0.01 μm to 0.3 μm .

21. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the release layer contains a binder belonging to the same binder group as that a binder contained in the ceramic green sheet belongs to and the agglutinant layer contains a binder belonging to the same binder group as that the binder contained in the release layer belongs to.

22. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 20, wherein the release layer contains a binder belonging to the same binder group as that a binder contained in the ceramic green sheet belongs to and the agglutinant layer contains a binder belonging to the same binder group as that the binder contained in the release layer belongs to.

23. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the release layer contains a plasticizing agent belonging to the same plasticizing agent group as that a plasticizing agent contained in the ceramic green sheet belongs to and the agglutinant layer contains a plasticizing agent belonging to the same plasticizing agent group as that the plasticizing agent contained in the release layer belongs to.

24. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 20, wherein the release layer contains a plasticizing agent belonging to the same plasticizing agent group as that a plasticizing agent contained in the ceramic green sheet belongs to and the agglutinant layer contains a plasticizing agent belonging to the same plasticizing agent group as that the plasticizing agent contained in the release layer belongs to.

25. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the release layer contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet and the agglutinant layer contains dielectric particles having the same composition as that of dielectric particles contained in the release layer.

26. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 20, wherein the release layer contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet and the agglutinant layer contains dielectric particles having the same composition as that of dielectric particles contained in the release layer.

27. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer contains an ampholytic surfactant in an amount smaller than that of the binder.

28. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 20, wherein the agglutinant layer contains an ampholytic surfactant in an amount smaller than that of the binder.

29. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

30. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 20, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

31. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet has a thickness equal to or thinner than 3 μm .

32. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 20, wherein the ceramic green sheet has a thickness equal to or thinner than 3 μm .

33. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the multi-layered unit includes a spacer layer formed on the surface of the release layer in a complementary pattern to that of the electrode layer.

34. (New) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 20, wherein the multi-layered unit includes a spacer layer formed on the surface of the release layer in a complementary pattern to that of the electrode layer.